

Abstract

The purpose of the present invention is to provide: a resin material that has a novel structure and that can be suitably used in a printed wiring board; and a resin composition which contains this resin material, which is excellent in coating property on a base material and also which yields a cured product having excellent heat resistance dielectric properties, and adhesion to a metal foil and a base material having low roughness. In order to achieve the foregoing, a polyimide resin is used, the polyimide resin being a copolymer of: an amino compound (A) containing a straight chain aliphatic diamino compound (a1), which has amino groups at both terminals, 1-4 methyl groups and/or ethyl groups in the side chains and 17-24 carbon atoms in the main chain, and an aromatic diamino compound (a2); and a tetrabasic acid dianhydride (B).

[No figure]